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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 15V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16hv540t-20-ss

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An errata sheet may exist for current devices, describing minor operational differences (from the data sheet) and recommended workarounds. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

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Corrections to this Data Sheet

We constantly strive to improve the quality of all our products and documentation. We have spent a great deal of time to ensure that this document is correct. However, we realize that we may have missed a few things. If you find any information that is missing or appears in error, please:

- Fill out and mail in the reader response form in the back of this data sheet.
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We appreciate your assistance in making this a better document.

TABLE 3-1: PINOUT DESCRIPTION - PIC16HV540

Name	DIP, SOIC No.	SSOP No.	I/O/P Type	Input Levels	Description	
RA0	17	19	I/O	TTL	Independently regulated Bi-directional I/O port — VIO	
RA1	18	20	I/O	TTL		
RA2	1	1	I/O	TTL		
RA3	2	2	I/O	TTL		
RB0	6	7	I/O	TTL	High-voltage Bi-directional I/O port. Sourced from VDD.	Wake-up on pin change
RB1	7	8	I/O	TTL		
RB2	8	9	I/O	TTL		
RB3	9	10	I/O	TTL		
RB4	10	11	I/O	TTL		
RB5	11	12	I/O	TTL		
RB6	12	13	I/O	TTL		
RB7	13	14	I/O	TTL		Wake-up on SLOW rising pin change.
T0CKI	3	3	I	ST	Clock input to Timer 0. Must be tied to VSS or VDD, if not in use, to reduce current consumption.	
$\overline{MCLR}$/VPP	4	4	I	ST	Master clear (reset) input/programming voltage input. This pin is an active low reset to the device. Voltage on the $\overline{MCLR}$/VPP pin must not exceed VDD[(1)] to avoid unintended entering of programming mode.	
OSC1/CLKIN	16	18	I	ST	Oscillator crystal input/external clock source input.	
OSC2/CLKOUT	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2/CLKOUT output is connected to TMR0, bit 0. Frequencies of CLKIN/8 to CLKIN/1024 can be generated on this pin.	
VDD	14	15,16	P	—	Positive supply.	
VSS	5	5,6	P	—	Ground reference.	

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input.

Note 1: VDD during programming mode can not exceed parameter PD1 called out in the PIC16C5X Programming Specification (Literature number DS30190).

3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter is incremented every Q1, and the instruction is fetched from program memory and latched into instruction register in Q4. It is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2 and Example 3-1.

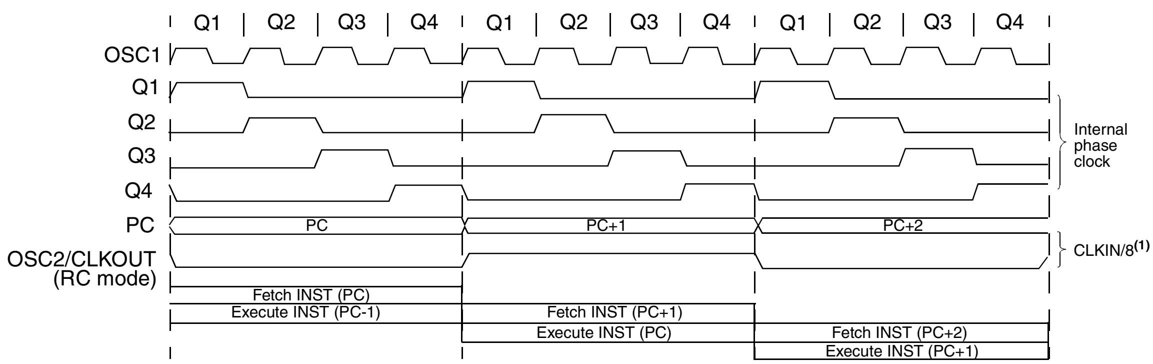
3.2 Instruction Flow/Pipelining

An Instruction Cycle consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., `GOTO`) then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-2: CLOCK/INSTRUCTION CYCLE



Note 1: Frequencies of CLKIN8 to CLKIN/1024 are possible.

EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW

1. MOVLW 55H	Fetch 1	Execute 1				
2. MOVWF PORTB		Fetch 2	Execute 2			
3. CALL SUB_1			Fetch 3	Execute 3		
4. BSF PORTA, BIT3				Fetch 4	Flush	
					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline while the new instruction is being fetched and then executed.

4.4 OPTION Register

The OPTION register is a 6-bit wide, write-only register which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the `OPTION` instruction, the contents of the W register will be transferred to the OPTION register. A RESET sets the OPTION<5:0> bits.

Example 4-1 illustrates how to initialize the OPTION register.

EXAMPLE 4-1: INSTRUCTIONS FOR INITIALIZING OPTION REGISTER

```
movlw   '0000 0111'b   ; load OPTION setup value into W
OPTION                 ; initialize OPTION register
```

REGISTER 4-2: OPTION REGISTER

U-0	U-0	W-1	W-1	W-1	W-1	W-1	W-1
—	—	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							0

W = Writable bit
U = Unimplemented bit
- n = Value at POR reset

bit 7-6: **Unimplemented**

bit 5: **T0CS**: Timer0 Clock Source Select bit
1 = Transition on T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: Timer0 Source Edge Select bit
1 = Increment on high-to-low transition on T0CKI pin
0 = Increment on low-to-high transition on T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler assigned to the WDT
0 = Prescaler assigned to Timer0

bit 2-0: **PS<2:0>**: Prescaler Rate Select bits

Bit Value	Timer0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

4.8 Indirect Data Addressing; INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 4-3: INDIRECT ADDRESSING

- Register file 05 contains the value 10h
- Register file 06 contains the value 0Ah
- Load the value 05 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 06)
- A read of the INDR register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected).

A simple program to clear RAM locations 10h-1Fh using indirect addressing is shown in Example 4-4.

EXAMPLE 4-4: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

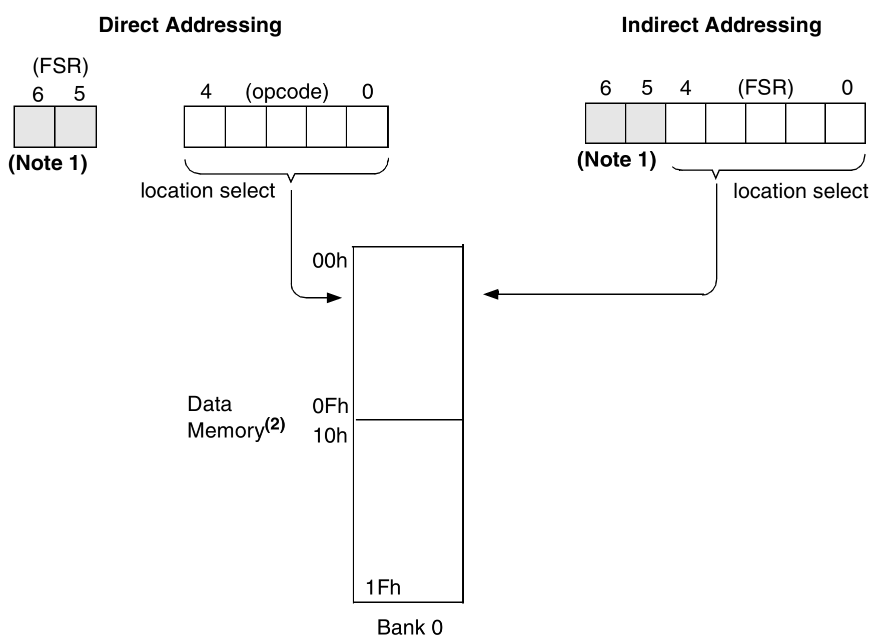
```
         movlw   0x10    ;initialize pointer
         movwf   FSR     ; to RAM
NEXT     clrf    INDF    ;clear INDF register
         incf    FSR,F   ;inc pointer
         btfsc   FSR,4   ;all done?
         goto    NEXT    ;NO, clear next
CONTINUE
         :               ;YES, continue
```

The FSR is a 5-bit (PIC16HV540) wide register. It is used in conjunction with the INDF register to indirectly address the data memory area.

The FSR<4:0> bits are used to select data memory addresses 00h to 1Fh.

PIC16HV540: Do not use banking. FSR<6:5> are unimplemented and read as '1's.

FIGURE 4-4: DIRECT/INDIRECT ADDRESSING



Note 1: Bits 5 and 6 are unimplemented and read as 1's.

2: For register map detail, see Section 4.2.

5.0 I/O PORTS

As with any other register, the I/O registers can be written and read under program control. However, read instructions (e.g., `MOVF PORTB,W`) always read the I/O pins independent of the pin's input/output modes. On RESET, all I/O ports are defined as input (inputs are at hi-impedance) since the I/O control registers (TRISA, TRISB) are all set.

5.1 PORTA

PORTA is a 4-bit I/O register. Only the low order 4 bits are used (RA3:RA0). Bits 7-4 are unimplemented and read as '0's. The inputs will tolerate input voltages as high as V_{IO} and outputs will swing from V_{SS} to V_{IO}. The internal voltage regulator V_{IO} powers PORTA I/O pads. The internal regulator output, V_{IO}, is switchable between 3Vdc and 5Vdc, via the (RL) bit in the OPTION2 register.

5.2 PORTB

PORTB is an 8-bit I/O register (PORTB<7:0>). All 8 PORTB I/Os are high voltage I/O. The inputs will tolerate input voltages as high as V_{DD} and outputs will swing from V_{SS} to V_{DD}. In addition, 5 of the PORTB pins can be configured for the wake-up on change feature. Pins RB0, RB1, RB2 and RB3 latch the state of the pin at the onset of sleep mode. (No "dummy" read of the PORTB pins is required prior to executing the `SLEEP` instruction.) A level change on the input resets the device, implementing wake-up on pin change. The $\overline{\text{PCWUF}}$ bit in the status register is cleared to indicate that a pin change caused the reset. This feature can be enabled/disabled in the OPTION2 register.

PORTB pin RB7 also exhibits this wake-up on pin high feature but is specially adapted for a slow-rising input signal. This special feature prevents excessive power consumption when desiring long sleep periods without using the watchdog timer and prescaler. $\overline{\text{PCWUF}}$ bit in the status register is cleared to indicate that a pin change caused the reset. This feature can be enabled/disabled in the OPTION2 register.

Only pins configured as inputs can cause this wake-up on pin change to occur.

To prevent false wake-up on pin change events on pins RB<0:3>, the pin state must be driven to a logic 1 or logic 0 and not left floating during the "`SLEEP`" state. For pin RB7, the pin state must be driven to logic 0 and allowed to ramp to a logic 1 for correct operation.

5.3 TRIS Registers

The output driver control registers are loaded with the contents of the W register by executing the `TRIS f` instruction. A '1' from a TRIS register bit puts the corresponding output driver in a hi-impedance mode. A '0' puts the contents of the output data latch on the selected pins, enabling the output buffer.

Note:	A read of the ports reads the pins, not the output data latches. That is, if an output driver on a pin is enabled and driven high, but the external system is holding it low, a read of the port will indicate that the pin is low.

The TRIS registers are "write-only" and are set (output drivers disabled) upon RESET.

5.4 I/O Interfacing

The equivalent circuit for the PORTA and PORTB I/O pins are shown in Figure 5-1 through Figure 5-4. All ports may be used for both input and output operation. For input operations, these ports are non-latching. Any input must be present until read by an input instruction (e.g., `MOVF PORTB, W`). The outputs are latched and remain unchanged until the output latch is rewritten. To use a port pin as output, the corresponding direction control bit (in TRISA, TRISB) must be cleared (= 0). For use as an input, the corresponding TRIS bit must be set. Any I/O pin can be programmed individually as input or output.

FIGURE 5-1: BLOCK DIAGRAM OF PORTA<0:3> PINS

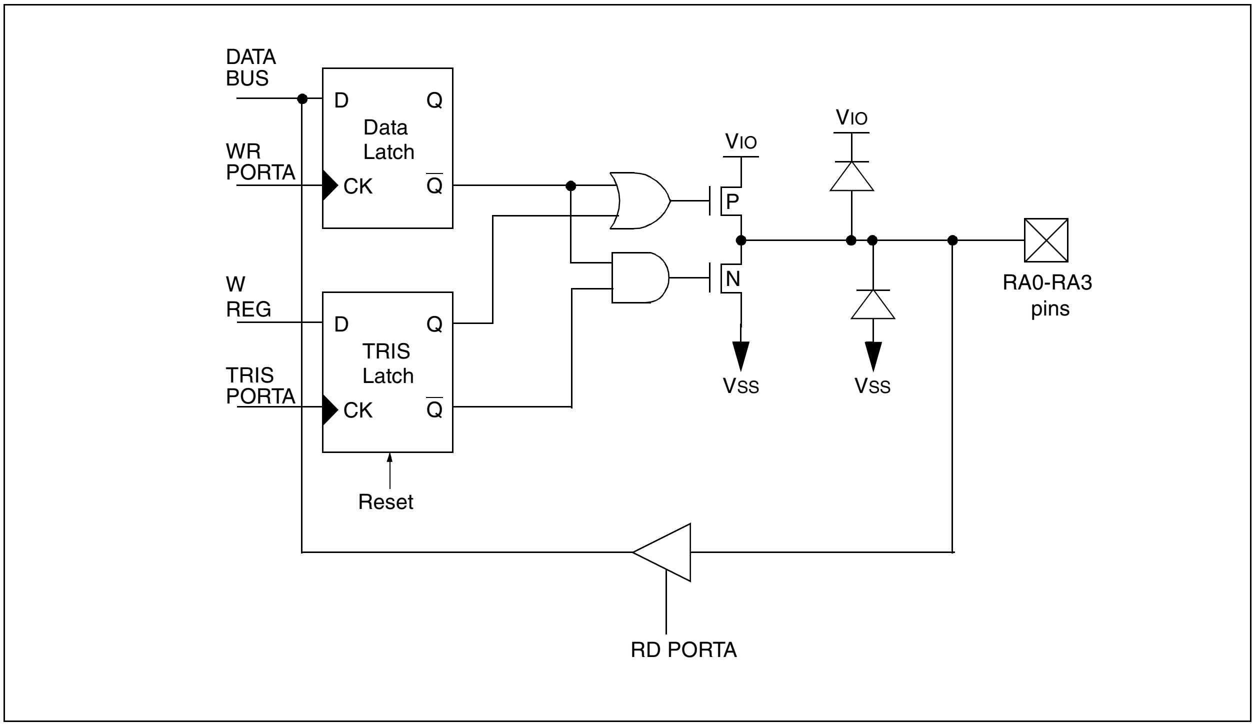


FIGURE 5-2: BLOCK DIAGRAM OF PORTB<0:3> PINS

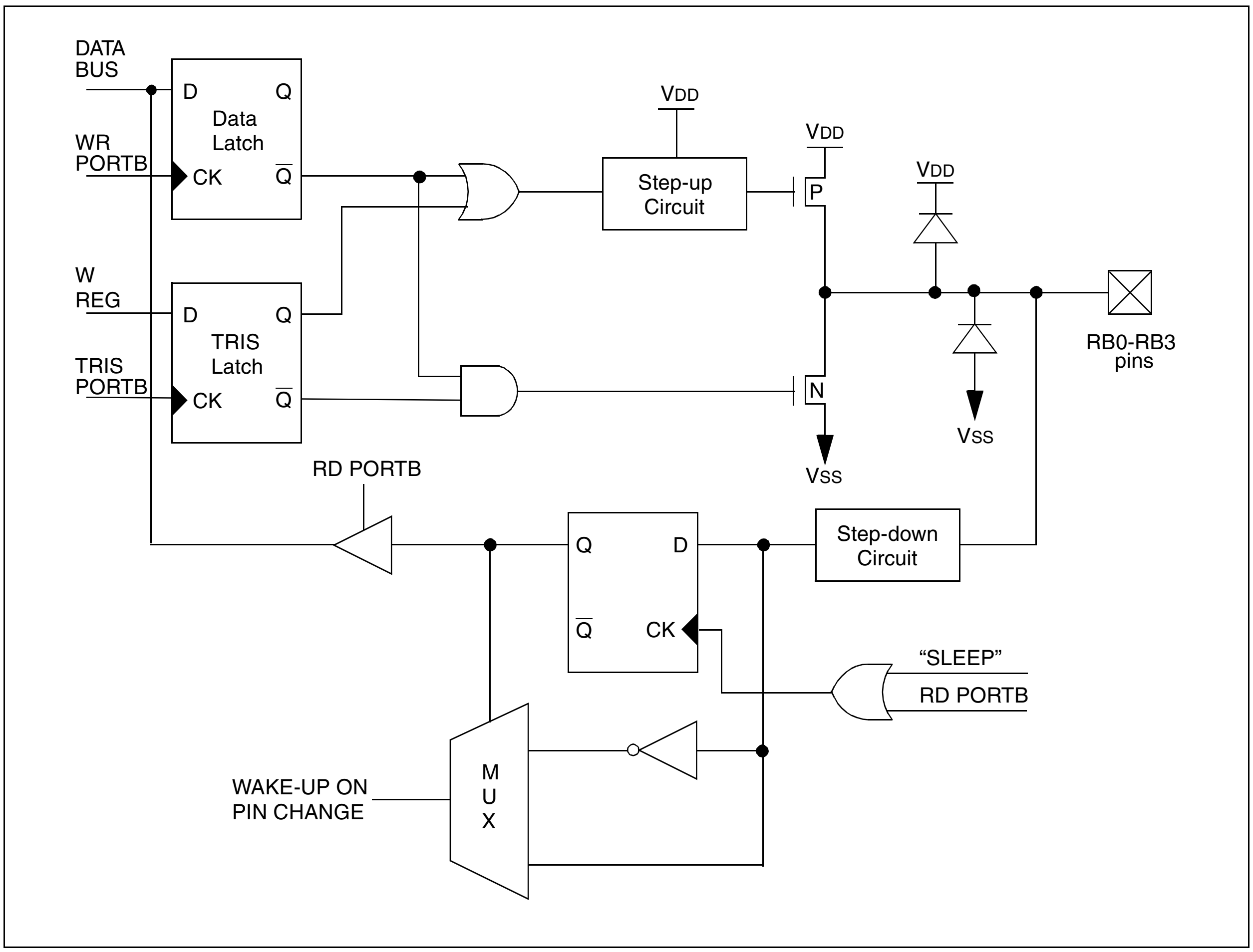
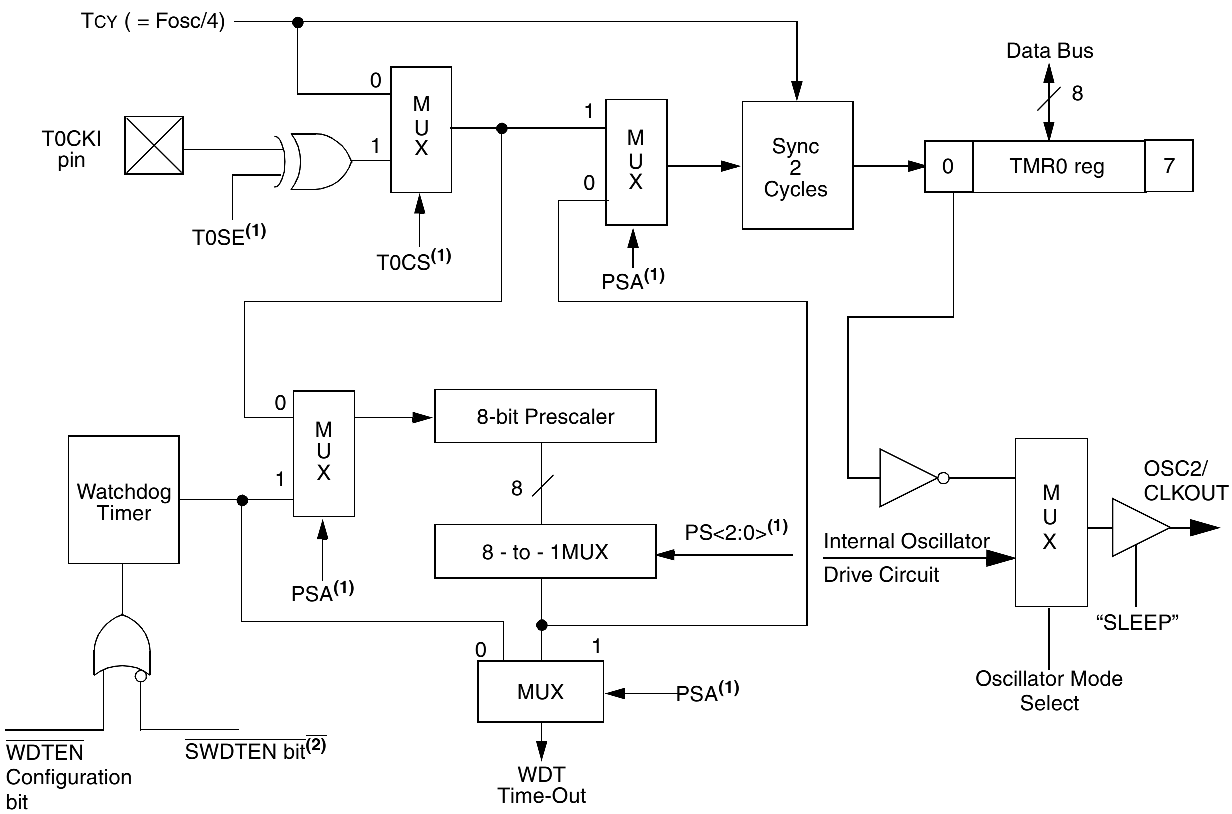


FIGURE 6-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note 1: T0CS, T0SE, PSA, PS<2:0> are bits in the OPTION register.

2: $\overline{\text{SWDTEN}}$ is a bit in the OPTION2 register.

7.2 Oscillator Configurations

7.2.1 OSCILLATOR TYPES

The PIC16HV540 can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

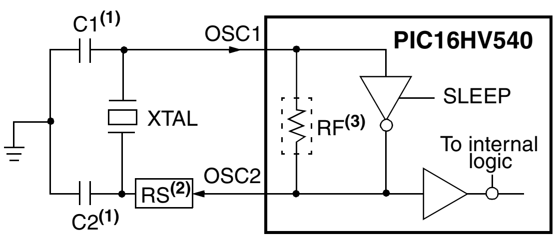
- LP: Low Power Crystal
- XT: Crystal/Resonator
- HS: High Speed Crystal/Resonator
- RC: Resistor/Capacitor

Note:	Not all oscillator selections available for all parts. See Section 7.1.

7.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 7-1). The PIC16HV540 oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source drive the OSC1/CLKIN pin (Figure 7-2).

FIGURE 7-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Capacitor Selection tables for recommended values of C1 and C2.
2: A series resistor (RS) may be required for AT strip cut crystals.
3: RF varies with the crystal chosen (approx. value = 10 MΩ).

FIGURE 7-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

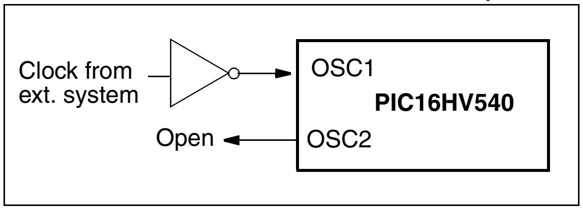


TABLE 7-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS - PIC16HV540

Osc Type	Resonator Freq	Cap. Range C1	Cap. Range C2
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-33 pF 10-22 pF	68-100 pF 15-33 pF 10-22 pF
HS	8.0 MHz 16.0 MHz	10-22 pF 10 pF	10-22 pF 10 pF

Note: These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 7-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR - PIC16HV540

Osc Type	Resonator Freq	Cap.Range C1	Cap. Range C2
LP	32 kHz(1)	15 pF	15 pF
XT	100 kHz 200 kHz 455 kHz 1 MHz 2 MHz 4 MHz	15-30 pF 15-30 pF 15-30 pF 15-30 pF 15 pF 15 pF	200-300 pF 100-200 pF 15-100 pF 15-30 pF 15 pF 15 pF
HS	4 MHz 8 MHz 20 MHz	15 pF 15 pF 15 pF	15 pF 15 pF 15 pF

Note 1: For V_{DD} > 4.5V, C1 = C2 ≈ 30 pF is recommended.
2: These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

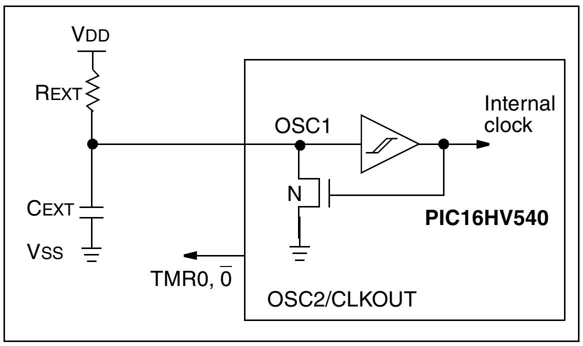
Note:	If you change from this device to another device, please verify oscillator characteristics in your application.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to VDD for given Rext/ Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

When used in RC mode, the CLKOUT pin can be used as a programmable clock output. The output is connected to TMR0, bit 0, and by setting the prescaler rate select bits, clock out frequencies of CLKIN/8 to CLKIN/1024 can be generated.

FIGURE 7-5: RC OSCILLATOR MODE



Note:	If you change from this device to another device, please verify oscillator characteristics in your application.

7.3 Reset

PIC16HV540 devices may be reset in one of the following ways:

- Power-On Reset (POR)
- $\overline{\text{MCLR}}$ reset (normal operation)
- $\overline{\text{MCLR}}$ wake-up reset (from SLEEP)
- WDT reset (normal operation)
- WDT wake-up reset (from SLEEP)
- Wake-up from SLEEP on Pin Change
- Brown-out Detect

Table 7-3 shows these reset conditions for the PCL and STATUS registers.

Some registers are not affected in any reset condition. Their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a "reset state" on Power-On Reset (POR), $\overline{\text{MCLR}}$ or WDT Reset. A $\overline{\text{MCLR}}$, WDT Wake-up from SLEEP or Wake-up from SLEEP on Pin Change also results in a device RESET, and not a continuation of operation before SLEEP.

The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits (STATUS <4:3>) and $\overline{\text{PCWUF}}$ (STATUS<7>) are set or cleared depending on the different reset conditions (Section 7.9). These bits may be used to determine the nature of the reset.

Table 7-4 lists a full description of reset states of all registers. Figure 7-6 shows a simplified block diagram of the on-chip reset circuit.

7.4 Power-On Reset (POR)

The PIC16HV540 incorporates on-chip Power-on Reset (POR) circuitry which provides an internal chip reset for most power-up situations. To use this feature, the user merely ties the $\overline{MCLR}$/VPP pin to VDD. A simplified block diagram of the on-chip Power-on Reset circuit is shown in Figure 7-7.

The Power-on Reset circuit and the Device Reset Timer (Section 7.5) circuit are closely related. On power-up, the reset latch is set and the DRT is reset. The DRT timer begins counting once it detects $\overline{MCLR}$ to be high. After the time-out period, which is typically 18 ms, it will reset the reset latch and thus end the on-chip reset signal.

A power-up example where $\overline{MCLR}$ is not tied to VDD is shown in Figure 7-8. VDD is allowed to rise and stabilize before bringing $\overline{MCLR}$ high. The chip will actually come out of reset TDRT msec after $\overline{MCLR}$ goes high.

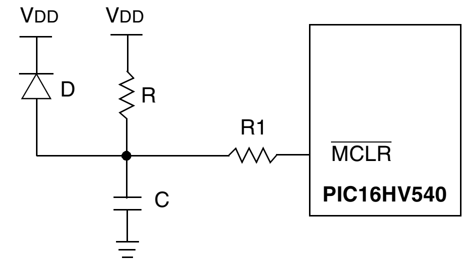
In Figure 7-9, the on-chip Power-on Reset feature is being used ($\overline{MCLR}$ and VDD are tied together). The VDD is stable before the start-up timer times out and there is no problem in getting a proper reset. However, Figure 7-10 depicts a problem situation where VDD rises too slowly. The time between when the DRT senses a high on the $\overline{MCLR}$/VPP pin, and when the $\overline{MCLR}$/VPP pin (and VDD) actually reach their full value, is too long. In this situation, when the start-up timer times out, VDD has not reached the VDD (min) value and the chip is, therefore, not guaranteed to function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 7-7).

Note:	When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For more information on PIC16HV540 POR, see *Power-Up Considerations* - AN522 in the Embedded Control Handbook.

The POR circuit does not produce an internal reset when VDD declines.

FIGURE 7-7: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



- External Power-On Reset circuit is required only if VDD power-up is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
- R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device electrical specification.
- R1 = 100Ω to 1 kΩ will limit any current flowing into $\overline{MCLR}$ from external capacitor C in the event of $\overline{MCLR}$ pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

SLEEP **Enter SLEEP Mode**

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT;
0 → WDT prescaler;
1 → $\overline{TO}$;
0 → $\overline{PD}$
1→ $\overline{PCWUF}$

Status Affected: $\overline{TO}$, $\overline{PD}$, $\overline{PCWUF}$

Encoding:

0000	0000	0011

Description: Time-out status bit ($\overline{TO}$) is set. The power down status bit ($\overline{PD}$) is cleared. The WDT and its prescaler are cleared.

The processor is put into SLEEP mode with the oscillator stopped. See section on SLEEP for more details.

Words: 1

Cycles: 1

Example: `SLEEP`

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \leq f \leq 31$
$d \in [0,1]$

Operation: (f) – (W) → (dest)

Status Affected: C, DC, Z

Encoding:

0000	10df	ffff

Description: Subtract (2's complement method) the W register from register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example 1: `SUBWF REG1, 1`

Before Instruction
REG1 = 3
W = 2
C = ?

After Instruction
REG1 = 1
W = 2
C = 1 ; result is positive

Example 2:

Before Instruction
REG1 = 2
W = 2
C = ?

After Instruction
REG1 = 0
W = 2
C = 1 ; result is zero

Example 3:

Before Instruction
REG1 = 1
W = 2
C = ?

After Instruction
REG1 = FF
W = 2
C = 0 ; result is negative

9.4 MPLINK/MPLIB Linker/Librarian

MPLINK is a relocatable linker for MPASM and MPLAB-C17 and MPLAB-C18. It can link relocatable objects from assembly or C source files along with pre-compiled libraries using directives from a linker script.

MPLIB is a librarian for pre-compiled code to be used with MPLINK. When a routine from a library is called from another source file, only the modules that contains that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications. MPLIB manages the creation and modification of library files.

MPLINK features include:

- MPLINK works with MPASM and MPLAB-C17 and MPLAB-C18.
- MPLINK allows all memory areas to be defined as sections to provide link-time flexibility.

MPLIB features include:

- MPLIB makes linking easier because single libraries can be included instead of many smaller files.
- MPLIB helps keep code maintainable by grouping related modules together.
- MPLIB commands allow libraries to be created and modules to be added, listed, replaced, deleted, or extracted.

9.5 MPLAB-SIM Software Simulator

The MPLAB-SIM Software Simulator allows code development in a PC host environment by simulating the PICmicro series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file or user-defined key press to any of the pins. The execution can be performed in single step, execute until break, or trace mode.

MPLAB-SIM fully supports symbolic debugging using MPLAB-C17 and MPLAB-C18 and MPASM. The Software Simulator offers the flexibility to develop and debug code outside of the laboratory environment making it an excellent multi-project software development tool.

9.6 MPLAB-ICE High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB-ICE Universal In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers (MCUs). Software control of MPLAB-ICE is provided by the MPLAB Integrated Development Environment (IDE), which allows editing, “make” and download, and source debugging from a single environment.

Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB-ICE allows expansion to support new PICmicro microcontrollers.

The MPLAB-ICE Emulator System has been designed as a real-time emulation system with advanced features that are generally found on more expensive development tools. The PC platform and Microsoft® Windows 3.x/95/98 environment were chosen to best make these features available to you, the end user.

MPLAB-ICE 2000 is a full-featured emulator system with enhanced trace, trigger, and data monitoring features. Both systems use the same processor modules and will operate across the full operating speed range of the PICmicro MCU.

9.7 PICMASTER/PICMASTER CE

The PICMASTER system from Microchip Technology is a full-featured, professional quality emulator system. This flexible in-circuit emulator provides a high-quality, universal platform for emulating Microchip 8-bit PICmicro microcontrollers (MCUs). PICMASTER systems are sold worldwide, with a CE compliant model available for European Union (EU) countries.

9.8 ICEPIC

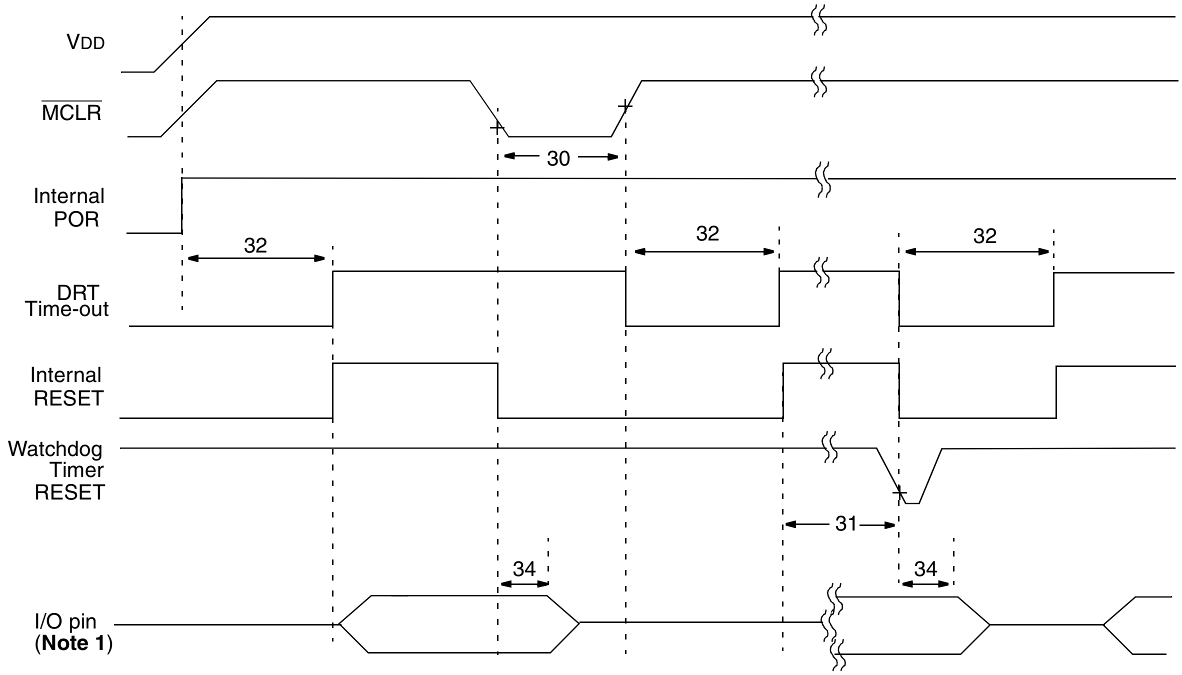
ICEPIC is a low-cost in-circuit emulation solution for the Microchip Technology PIC16C5X, PIC16C6X, PIC16C7X, and PIC16CXXX families of 8-bit one-time-programmable (OTP) microcontrollers. The modular system can support different subsets of PIC16C5X or PIC16CXXX products through the use of interchangeable personality modules or daughter boards. The emulator is capable of emulating without target application circuitry being present.

9.9 MPLAB-ICD In-Circuit Debugger

Microchip’s In-Circuit Debugger, MPLAB-ICD, is a powerful, low-cost run-time development tool. This tool is based on the flash PIC16F877 and can be used to develop for this and other PICmicro microcontrollers from the PIC16CXXX family. MPLAB-ICD utilizes the In-Circuit Debugging capability built into the PIC16F87X. This feature, along with Microchip’s In-Circuit Serial Programming protocol, offers cost-effective in-circuit flash programming and debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time. The MPLAB-ICD is also a programmer for the flash PIC16F87X family.

NOTES:

FIGURE 10-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16HV540



Note 1: I/O pins must be taken out of hi-impedance mode by enabling the output drivers in software.

FIGURE 10-5: BROWN-OUT DETECT TIMING

11.0 DC AND AC CHARACTERISTICS - PIC16HV540

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed. In some graphs or tables the data presented are outside specified operating range (e.g., outside specified VDD range). This is for information only and devices will operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time. "Typical" represents the mean of the distribution while "max" or "min" represents (mean + 3σ) and (mean – 3σ) respectively, where σ is standard deviation.

FIGURE 11-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

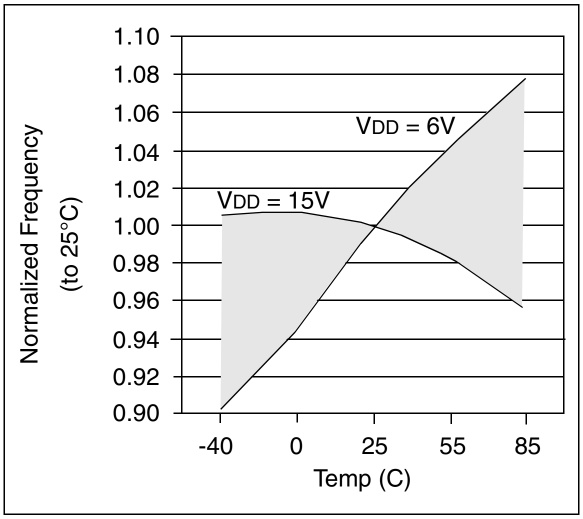


TABLE 11-1: RC OSCILLATOR FREQUENCIES

CEXT	REXT	Average FOSC, VIO = 5V	
		25°C, VDD = 6V	25°C, VDD = 15V
20 pF	3.3k	4986.7 kHz	(1)
	5k	4233.3 kHz	(1)
	10k	2656.7 kHz	5150.0 kHz
	24k	1223.3 kHz	3286.7 kHz
	100k	325.7 kHz	955.7 kHz
	390k	79.0 kHz	250.7 kHz
100 pF	3.3k	1916.7 kHz	(1)
	5k	1593.3 kHz	(1)
	10k	995.7 kHz	2086.7 kHz
	24k	448.3 kHz	1210.0 kHz
	100k	116.0 kHz	355.7 kHz
	390k	28.3 kHz	89.7 kHz
300 pF	3.3k	744 kHz	(1)
	5k	620.3 kHz	(1)
	10k	382.0 kHz	817.3 kHz
	24k	169.7 kHz	483.0 kHz
	100k	44.1 kHz	135.7 kHz
	390k	10.6 kHz	34.4 kHz

Note 1: This combination of R, C and VDD draws too much current and prohibits oscillator operation.

FIGURE 11-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD (CEXT = 20pF)

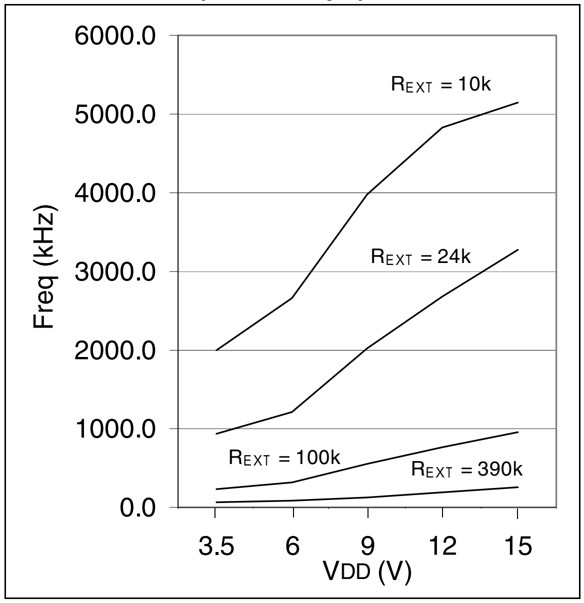
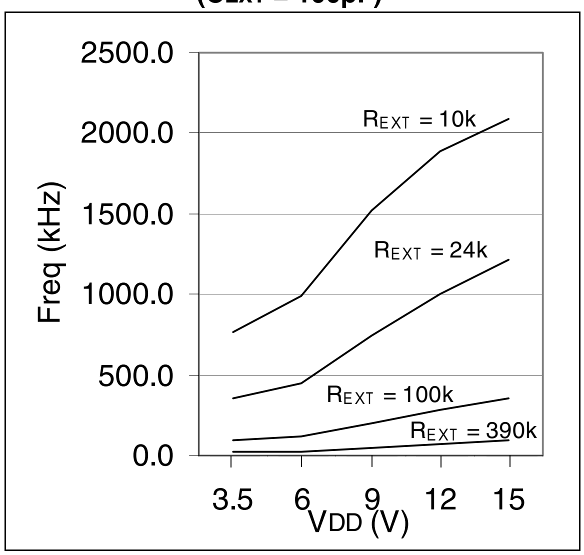
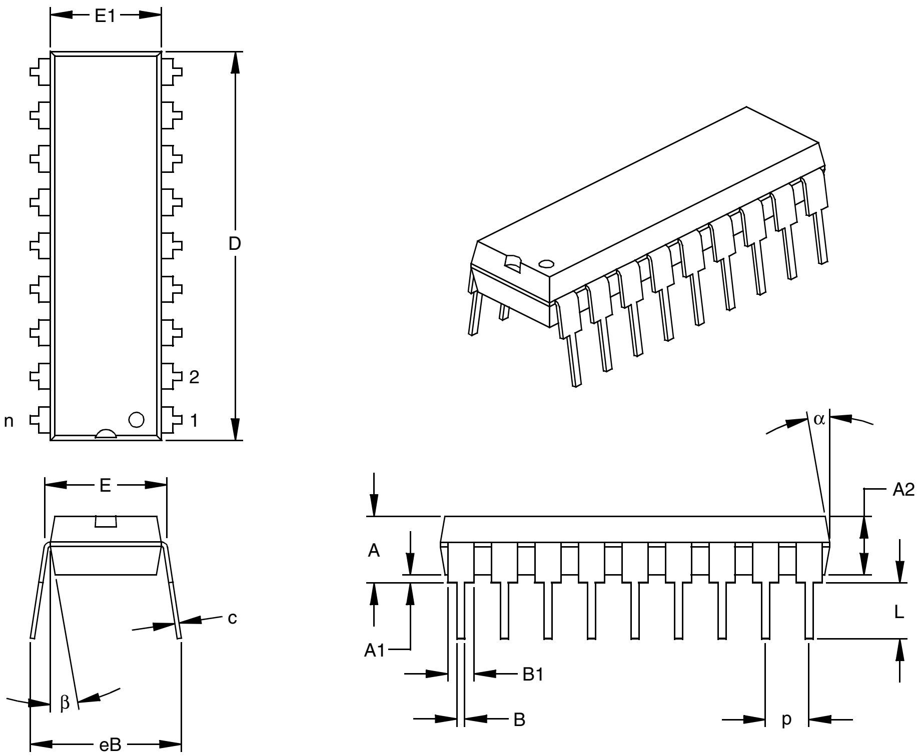


FIGURE 11-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD (CEXT = 100pF)



12.0 PACKAGING INFORMATION

12.1 18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

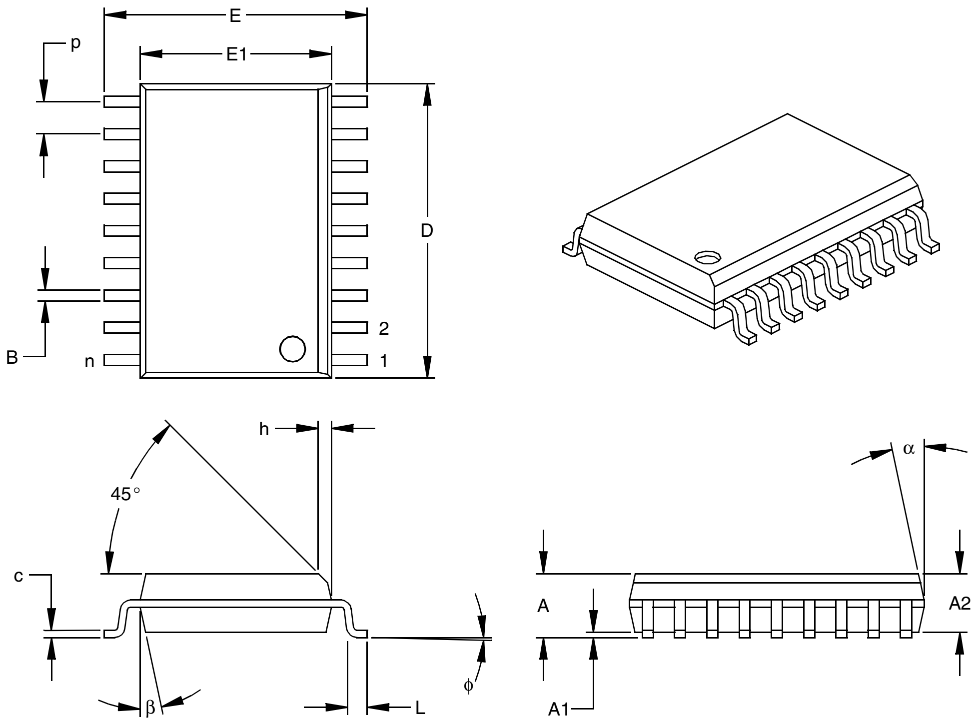


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-001
Drawing No. C04-007

12.2 18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

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www.microchip.com

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